

OL-TFA9897

wafer level chip-scale package; 30 bumps; 2.06 x 2.72 x 0.50 mm

8 February 2016

Package information

1. Package summary

Terminal position code	B (bottom)
Package type descriptive code	WLCSP
Package type industry code	WLCSP
Package style descriptive code	UC (uncased chip)
Package style suffix code	NA (not applicable)
Package body material type	X (other)
Mounting method type	S (surface mount)
Issue date	9-10-2014

Table 1. Package summary

Symbol	Parameter		Min	Typ	Nom	Max	Unit
D	package length		2.69	-	2.72	2.75	mm
E	package width		2.03	-	2.06	2.09	mm
A	seated height		0.45	-	0.5	0.55	mm
A ₂	package height		0.28	-	0.3	0.32	m
e	nominal pitch		-	-	0.4	-	mm
n ₂	actual quantity of termination		-	-	30	-	



2. Package outline

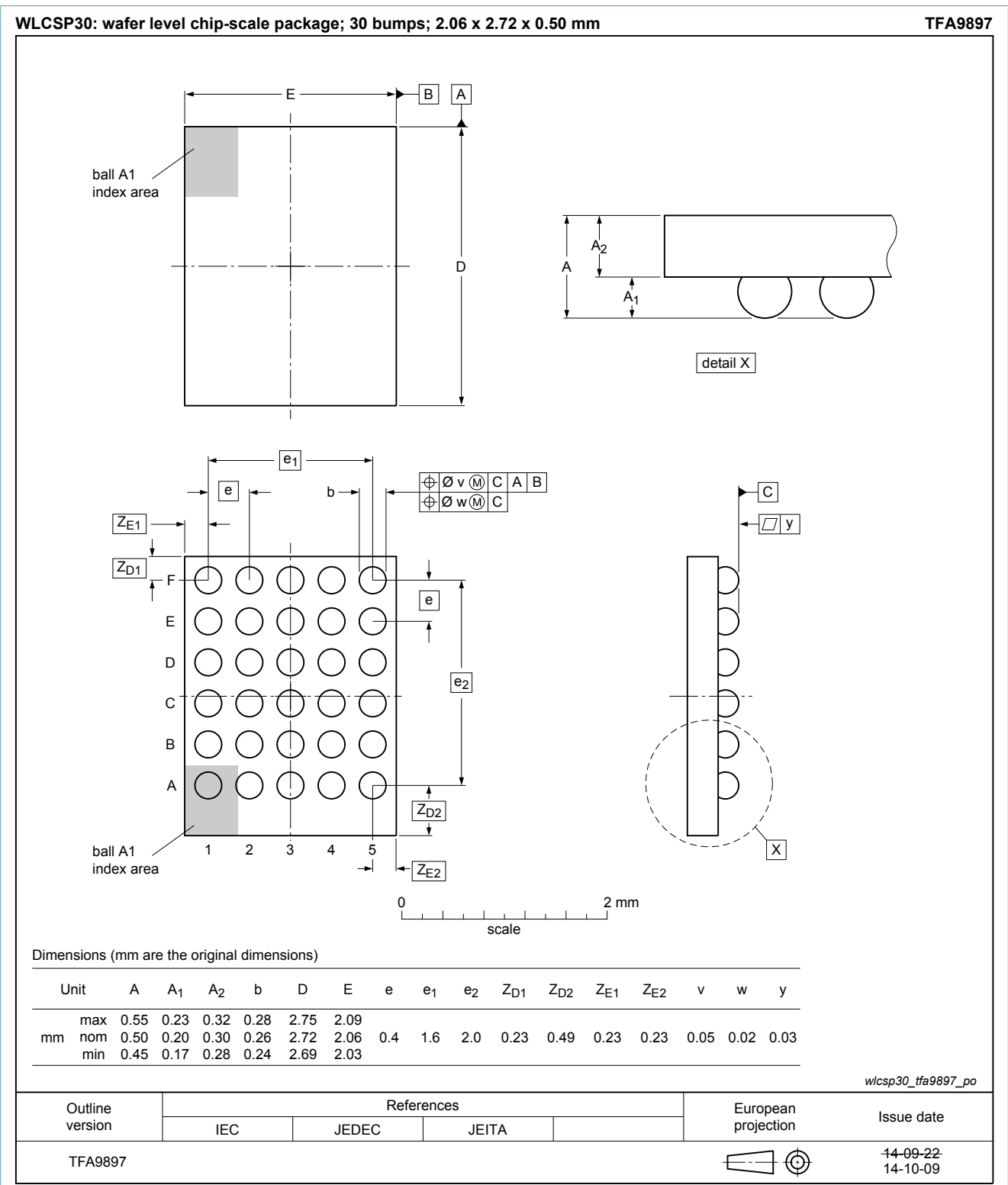


Fig. 1. Package outline WLCSP (OL-TFA9897)

3. Legal information

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